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April 2000 Revised January 2005

## NC7WZ38

# TinyLogic® UHS Dual 2-Input NAND Gate (Open Drain Output)

## **General Description**

The NC7WZ38 is a dual 2-Input NAND Gate with open drain output stage from Fairchild's Ultra High Speed Series of TinyLogic®. The device is fabricated with advanced CMOS technology to achieve ultra high speed with high output drive while maintaining low static power dissipation over a very broad  $V_{\rm CC}$  operating range. The device is specified to operate over the 1.65V to 5.5V  $V_{\rm CC}$  range. The inputs and output are high impedance when  $V_{\rm CC}$  is 0V. Inputs tolerate voltages up to 7V independent of  $V_{\rm CC}$  operating voltage. The open drain output stage will tolerate voltages up to 7V independent of  $V_{\rm CC}$  when in the high impedance state.

#### **Features**

- Space saving US8 surface mount package
- MicroPak™ Pb-Free leadless package
- Open Drain output stage for OR tied applications
- Ultra High Speed; t<sub>PD</sub> 2.2 ns Typ into 50 pF at 5V V<sub>CC</sub>
- High Output Sink Drive; 24 mA at 3V V<sub>CC</sub>
- Broad V<sub>CC</sub> Operating Range; 1.65V to 5.5V
- $\blacksquare$  Matches the performance of LCX when operated at 3.3V  $V_{CC}$
- Power down high impedance inputs/output
- Overvoltage Tolerant inputs facilitate 5V to 3V translation
- Patented noise/EMI reduction circuitry implemented

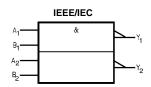
### **Ordering Code:**

Order Number	Package Number	Product Code Top Mark	Package Description	Supplied As
NC7WZ38K8X	MAB08A	WZ38	8-Lead US8, JEDEC MO-187, Variation CA 3.1mm Wide	3k Units on Tape and Reel
NC7WZ38L8X	MAC08A	U5	Pb-Free 8-Lead MicroPak, 1.6 mm Wide	5k Units on Tape and Reel

Pb-Free package per JEDEC J-STD-020B.

 $\label{eq:total_cond} \mbox{TinyLogio} \mbox{$\mathbb{B}$ is a registered trademark of Fairchild Semiconductor Corporation.} \\ \mbox{MicroPak}^{\mbox{$\mathbb{M}$}} \mbox{$\mathbb{M}$ is a trademark of Fairchild Semiconductor Corporation.} \\$ 

## **Logic Symbol**



## **Pin Descriptions**

Pin Names	Description
A <sub>n</sub> , B <sub>n</sub>	Inputs
Y <sub>n</sub>	Output

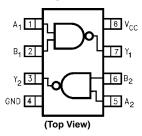
## **Function Table**

 $Y = \overline{AB}$ 

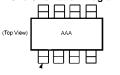
Inp	Output			
Α	A B			
L	L	*H		
L	Н	*H		
Н	L	*H		
Н	Н	L		

H = HIGH Logic Level L = LOW Logic Level \*H = HIGH Impedance output state (Open Drain)

## **Connection Diagrams**



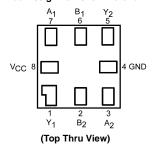
## Pin One Orientation Diagram



AAA represents Product Code Top Mark - see ordering code

**Note:** Orientation of Top Mark determines Pin One location. Read the top product code mark left to right, Pin One is the lower left pin (see diagram).

#### Pad Assignments for MicroPak



### **Absolute Maximum Ratings**(Note 1)

-0.5V to +7V Supply Voltage (V<sub>CC</sub>) DC Input Voltage (V<sub>IN</sub>) -0.5V to +7V -0.5V to +7VDC Output Voltage (V<sub>OUT</sub>) DC Input Diode Current (I<sub>IK</sub>)

 $@V_{IN} < -0.5V$ -50 mA

DC Output Diode Current (IOK)

@V<sub>OUT</sub> < -0.5V -50 mA DC Output Current (I<sub>OUT</sub>) +50 mA DC V<sub>CC</sub>/GND Current (I<sub>CC</sub>/I<sub>GND</sub>) ±100 mA Storage Temperature (T<sub>STG</sub>)  $-65^{\circ}C$  to  $+150^{\circ}C$ 

Junction Temperature under Bias (T<sub>J</sub>) Junction Lead Temperature (T<sub>L</sub>);

260°C (Soldering, 10 seconds) Power Dissipation (P<sub>D</sub>) @  $+85^{\circ}$ C 250 mW

## **Recommended Operating** Conditions (Note 2)

Supply Voltage Operating ( $V_{CC}$ ) 1.65V to 5.5V 1.5V to 5.5V Supply Voltage Data Retention (V<sub>CC</sub>) 0V to 5.5V Input Voltage (V<sub>IN</sub>) Output Voltage (V<sub>OUT</sub>) 0V to  $V_{\mbox{\footnotesize CC}}$ Operating Temperature (T<sub>A</sub>)  $-40^{\circ}\text{C}$  to  $+85^{\circ}\text{C}$ Input Rise and Fall Time (t<sub>r</sub>, t<sub>f</sub>)

 $V_{CC} = 1.8V \pm 0.15V, 2.5V \pm 0.2V$ 0 ns/V to 20 ns/V  $V_{CC} = 3.3V \pm 0.3V$ 0 ns/V to 10 ns/V

 $V_{CC} = 5.0V \pm 0.5V$ 0 ns/V to 5 ns/V 250°C/W

Thermal Resistance ( $\theta_{JA}$ )

Note 1: Absolute maximum ratings are DC values beyond which the device may be damaged or have its useful life impaired. The datasheet specifications should be met, without exception, to ensure that the system design is reliable over its power supply, temperature, and output/input loading variables. Fairchild does not recommend operation outside datasheet specifi-

Note 2: Unused inputs must be held HIGH or LOW. They may not float.

### **DC Electrical Characteristics**

Symbol	Parameter	V <sub>CC</sub>	1	Γ <sub>A</sub> = +25°C		$T_A = -40^{\circ}$	C to +85°C	Units	Conditions	
<b>C</b> ,	i didilicici	(V)	Min Typ		Max	Min Max		0	00.1411.0110	
V <sub>IH</sub>	HIGH Level	1.65 to 1.95	0.75 V <sub>CC</sub>			0.75 V <sub>CC</sub>		V		
	Input Voltage	2.3 to 5.5	0.7 V <sub>CC</sub>			0.7 V <sub>CC</sub>		v		
V <sub>IL</sub>	LOW Level	1.65 to 1.95			0.25 V <sub>CC</sub>		0.25 V <sub>CC</sub>	V		
	Input Voltage	2.3 to 5.5			$0.3~V_{\rm CC}$		$0.3  V_{\rm CC}$	v		
I <sub>LKG</sub>	HIGH Level Output Leakage	5.5			±5		±10	μА	$V_{IN} = V_{IL}$ $V_{OUT} = V_{CC}$	or GND
V <sub>OL</sub>	LOW Level	1.65		0.0	0.1		0.1			
	Output Voltage	2.3		0.0	0.1		0.1	V	., .,	400 /
		3.0		0.0	0.1		0.1	V	$V_{IN} = V_{IH}$	$I_{OL} = 100 \mu$
		4.5		0.0	0.1		0.1			
		1.65		0.08	0.24		0.24			$I_{OL} = 4 \text{ mA}$
		2.3		0.10	0.3		0.3			$I_{OL} = 8 \text{ mA}$
		3.0		0.15	0.4		0.4	V		I <sub>OL</sub> = 16 mA
		3.0		0.22	0.55		0.55			I <sub>OL</sub> = 24 mA
		4.5		0.22	0.55		0.55			$I_{OL} = 32 \text{ mA}$
I <sub>IN</sub>	Input Leakage Current	5.5			±0.1		±1	μΑ	$V_{IN} = 5.5V$ ,	GND
I <sub>OFF</sub>	Power Off Leakage Current	0.0			1		10	μΑ	V <sub>IN</sub> or V <sub>OUT</sub>	= 5.5V
Icc	Quiescent Supply Current	1.65 to 5.5			1		10	μΑ	$V_{IN} = 5.5V$ ,	GND

150°C

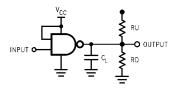
## **AC Electrical Characteristics**

Symbol	Parameter	V <sub>CC</sub>	$T_A = +25$ °C			T <sub>A</sub> = -40°	$T_A = -40^{\circ}C \text{ to } +85^{\circ}C$		Conditions	Figure
Cymbol		(V)	Min	Тур	Typ Max Min Max		Units	Number		
t <sub>PZL</sub>	Propagation Delay	$1.8 \pm 0.15$	2.0	5.2	9.2	2.0	9.6		C <sub>L</sub> = 50 pF	
		$2.5 \pm 0.2$	1.5	3.5	5.7	1.5	6.1	200	$RU=500\Omega$	Figures
		$3.3 \pm 0.3$	1.0	2.8	4.1	1.0	4.5	ns	$RD = 500\Omega$	1, 3
		$5.0 \pm 0.5$	0.5	2.2	3.4	0.5	3.6		$V_I = 2 \times V_{CC}$	
t <sub>PLZ</sub>	Propagation Delay	$1.8 \pm 0.15$	2.0	4.6	9.2	2.0	9.6		C <sub>L</sub> = 50 pF	
		$2.5 \pm 0.2$	1.5	3.2	5.7	1.5	6.1	ns	$RU=500\Omega$	Figures
		$3.3 \pm 0.3$	1.0	2.4	4.1	1.0	4.5	115	$RD = 500\Omega$	1, 3
		$5.0 \pm 0.5$	0.5	1.6	3.4	0.5	3.6		$V_I = 2 \times V_{CC}$	
C <sub>IN</sub>	Input Capacitance	0		2.5				pF		
C <sub>OUT</sub>	Output Capacitance	0		4.2				pF		
C <sub>PD</sub>	Power Dissipation	3.3		7				pF	(Note 3)	Figure 2
	Capacitance	5.0		9				PΓ	(Note 3)	i igule 2

Note 3: C<sub>PD</sub> is defined as the value of the internal equivalent capacitance which is derived from dynamic operating current consumption (I<sub>CCD</sub>) at no output loading and operating at 50% duty cycle. (See Figure 2.) C<sub>PD</sub> is related to I<sub>CCD</sub> dynamic operating current by the expression:

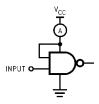
I<sub>CCD</sub> = (C<sub>PD</sub>) (V<sub>CC</sub>) (f<sub>IN</sub>) + (I<sub>CC</sub> static).

## **AC Loading and Waveforms**



 ${
m C_L}$  includes load and stray capacitance Input PRR = 1.0 MHz;  ${
m t_w}$  = 500 ns

FIGURE 1. AC Test Circuit



$$\label{eq:local_local_local_local} \begin{split} & \text{Input} = \text{AC Waveform; } t_r = t_f = 1.8 \text{ ns} \\ & \text{PRR} = 10 \text{ MHz; Duty Cycle} = 50\% \end{split}$$

FIGURE 2. I<sub>CCD</sub> Test Circuit

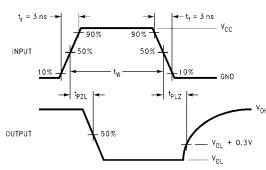


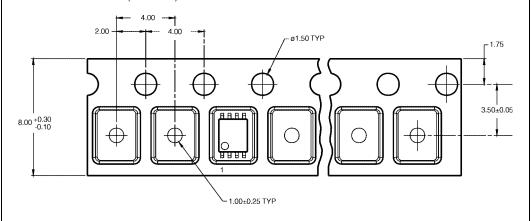
FIGURE 3. AC Waveforms

## **Tape and Reel Specification**

TAPE FORMAT for US8

Package	Tape	Number	Cavity	Cover Tape	
Designator	Section	Cavities	Status	Status	
K8X	Leader (Start End)	125 (typ)	Empty	Sealed	
	Carrier	3000	Filled	Sealed	
	Trailer (Hub End)	75 (typ)	Empty	Sealed	

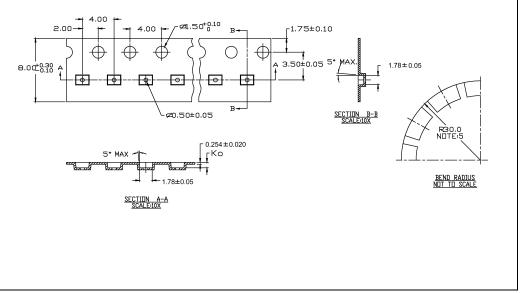
#### TAPE DIMENSIONS inches (millimeters)



TAPE FORMAT for MicroPak

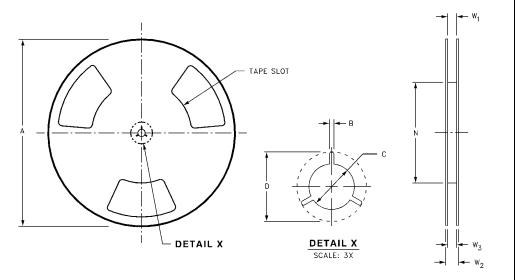
Package	Tape	Number	Cavity	Cover Tape Status	
Designator	Section	Cavities	Status		
	Leader (Start End)	125 (typ)	Empty	Sealed	
L8X	Carrier	3000	Filled	Sealed	
	Trailer (Hub End)	75 (typ)	Empty	Sealed	

## TAPE DIMENSIONS inches (millimeters)



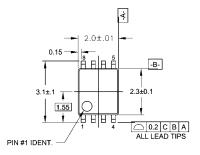
## Tape and Reel Specification (Continued)

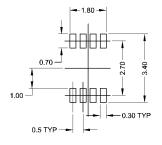
REEL DIMENSIONS inches (millimeters)



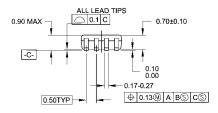
Tape Size	Α	В	C	D	N	W1	W2	W3
0	7.0	0.059	0.512	0.795	2.165	0.331 + 0.059/-0.000	0.567	W1 + 0.078/-0.039
8 mm	(177.8)	(1.50)	(13.00)	(20.20)	(55.00)	(8.40 + 1.50/-0.00)	(14.40)	(W1 + 2.00/-1.00)

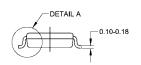
## Physical Dimensions inches (millimeters) unless otherwise noted

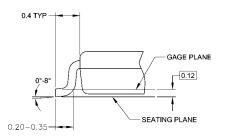




#### LAND PATTERN RECOMMENDATION







## NOTES:

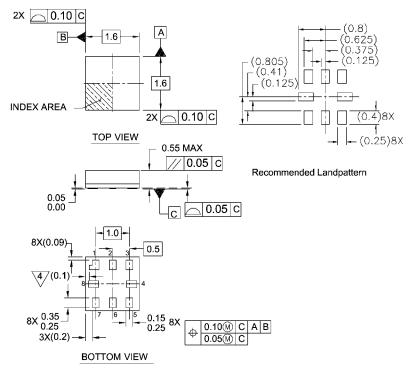
- CONFORMS TO JEDEC REGISTRATION MO-187
   B. DIMENSIONS ARE IN MILLIMETERS.
   C. DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH, AND TIE BAR EXTRUSIONS.
- D. DIMENSIONS AND TOLERANCES PER ANSI Y14.5M, 1982.

DETAIL A

#### MAB08AREVC

8-Lead US8, JEDEC MO-187, Variation CA 3.1mm Wide Package Number MAB08A

## Physical Dimensions inches (millimeters) unless otherwise noted (Continued)



#### Notes:

- 1. PACKAGE CONFORMS TO JEDEC MO-255 VARIATION UAAD
- 2. DIMENSIONS ARE IN MILLIMETERS
- 3. DRAWING CONFORMS TO ASME Y.14M-1994

4/PIN 1 FLAG, END OF PACKAGE OFFSET.

MAC08AREVC

Pb-Free 8-Lead MicroPak, 1.6 mm Wide Package Number MAC08A

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